

**What is claimed is:**

1                   1.     An electronics assembly comprising:  
2                   a heat generating component;  
3                   a heat sink positioned to define a gap between said heat  
4                   generating component and said heat sink;  
5                   at least one pre-cured thermal adhesive member positioned  
6                   within said gap creating a physical barrier between said heat generating  
7                   component and said heat sink; and  
8                   a post-cured thermal adhesive member filling said gap.

1                   2.     An electronics assembly as described in claim 1 wherein  
2                   said heat generating component is an electrical component.

1                   3.     An electronics assembly as described in claim 1 wherein  
2                   said at least one pre-cured thermal adhesive member is formed using droplets of  
3                   thermal adhesive.

1                   4.     An electronics assembly as described in claim 1 wherein  
2                   said at least one pre-cured thermal adhesive member is affixed to said heat  
3                   generating component prior to assembly.

1                   5.     An electronics assembly as described in claim 1 wherein  
2                   said at least one pre-cured thermal adhesive member is affixed to said heat sink  
3                   prior to assembly.

1                   6.     An electronics assembly as described in claim 1 further  
2                   comprising:  
3                   a substrate; and  
4                   at least one clamping mechanism attaching said substrate to said  
5                   heat sink.

1                   7.     An electronics assembly as described in claim 1 wherein  
2                   said heat sink is a metal case.

1                   8.    An electronics assembly as described in claim 1 wherein  
2   said heat sink includes a heat rail.

1                   9.    An electronics assembly as described in claim 1 wherein  
2   said heat sink includes a thermally conductive bracket.

1                   10.   An electronics assembly as described in claim 1 wherein  
2   said at least one pre-cured thermal adhesive member includes dots of equal  
3   height.

1                   11.   A method of applying thermal adhesive to an electronics  
2   assembly comprising:

3                   forming a plurality of pre-cure thermal adhesive members;  
4                   curing said plurality of pre-cure thermal adhesive members;  
5                   applying a post-cure thermal adhesive;  
6                   assembling an electronics assembly including a heat generating  
7   component and a heat sink such that said plurality of pre-cure thermal adhesive  
8   members and said post-cure thermal adhesive are positioned within a gap  
9   formed between said heat generating component and said heat sink; and  
10                  curing said post-cure thermal adhesive.

1                   12.   A method as described in claim 11 wherein said plurality  
2   of pre-cure thermal adhesive members are formed on said heat generating  
3   component.

1                   13.   A method as described in claim 11 wherein said plurality  
2   of pre-cure thermal adhesive members are formed in said heat sink.

1                   14.   A method as described in claim 11 wherein said heat  
2   generating component is an electrical component.

1                    15.    A method as described in claim 11 wherein said forming  
2                    a plurality of pre-cure thermal adhesive members includes forming droplets of  
3                    pre-cure thermal adhesive.

1                    16.    A method as described in claim 11 wherein said post-cure  
2                    thermal adhesive is applied to said heat generating component.

1                    17.    A method as described in claim 11 wherein said post-cure  
2                    thermal adhesive is applied to said heat sink.